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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	PowerPC e6500
Number of Cores/Bus Width	4 Core, 64-Bit
Speed	1.8GHz
Co-Processors/DSP	-
RAM Controllers	DDR3, DDR3L
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	1Gbps (8), 2.5Gbps (4), 10Gbps (4)
SATA	SATA 3Gbps (2)
USB	USB 2.0 + PHY (2)
Voltage - I/O	-
Operating Temperature	0°C ~ 105°C (TA)
Security Features	-
Package / Case	NI-1230-4LS2L
Supplier Device Package	NI-1230-4LS2L
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/t2080nsn7ttb

3 Application examples

This chip is well-suited for applications that are highly compute-intensive, I/O-intensive, or both.

3.1 1U security appliance

This figure shows a 1U security appliance built around a single SoC. The QorIQ DPAA accelerates basic packet classification, filtering, and packet queuing, while the crypto accelerator, regex accelerator, and compression/decompression accelerator perform high throughput content processing. The high single threaded and aggregate DMIPS of the core CPUs provide the processing horsepower for complex classification and flow state tracking required for proxying applications as well as heuristic traffic analysis and policy enforcement.

The SoC's massive integration significantly reduces system BOM cost. SATA hard drives connect directly to the SoC's integrated controllers, and an Ethernet switch is only required if more than eight 1 GE ports or 4 10 GE ports are required. The SoC supports PCIe and Serial RapidIO for expansion.

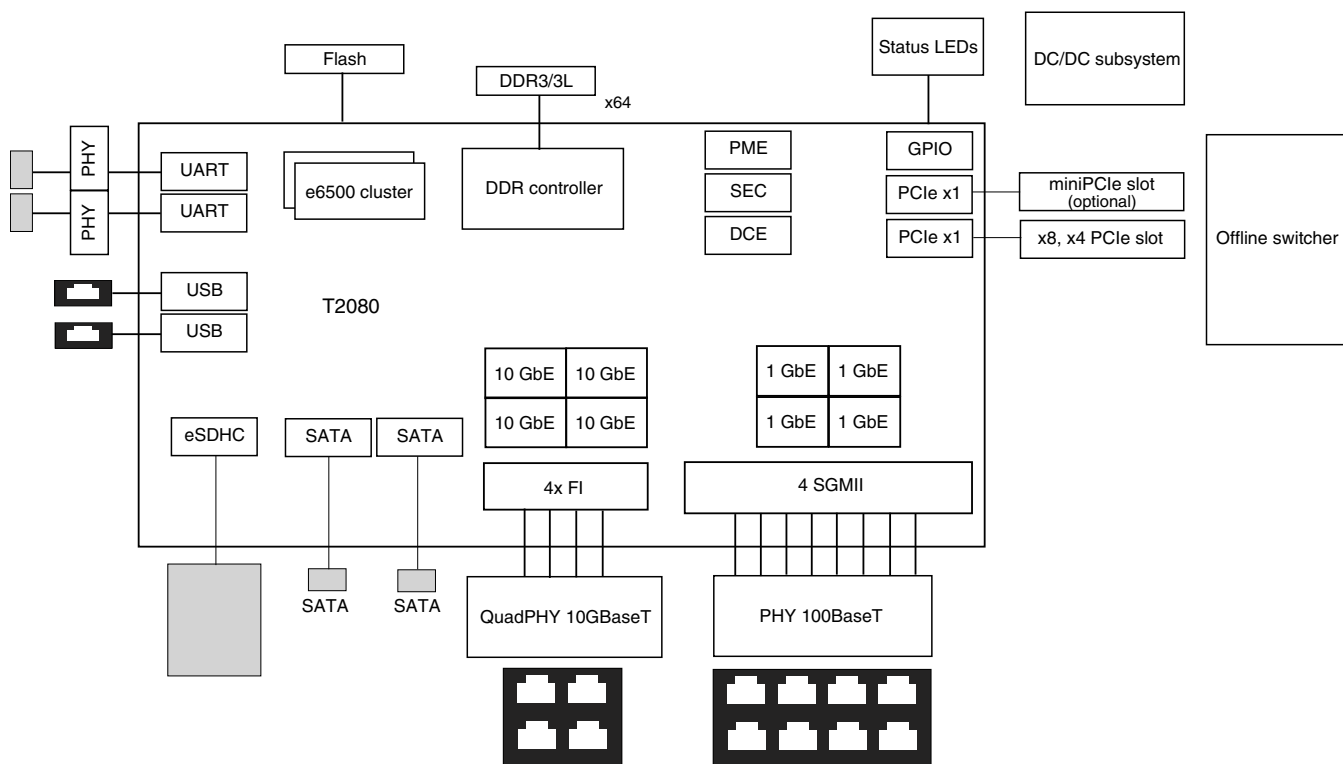


Figure 1. SoC 1U security appliance

3.2 Radio node controller

Some of the more demanding packet-processing applications are found in the realm of wireless infrastructure. These systems have to interwork between wireless link layer protocols and IP networking protocols. Wireless protocol complexity is high, and includes scheduling, retransmission, and encryption with algorithms specific to cellular wireless access networks. Connecting to the IP network offers wireless infrastructure tremendous cost savings, but introduces all the security threats found in the IP world. The chip's network and peripheral interfaces provide it with the flexibility to connect to DSPs, and to

wireless link layer framing ASICs/FPGAs . While the Data Path Acceleration Architecture offers encryption acceleration for both wireless and IP networking protocols, in addition to packet filtering capability on the IP networking side, multiple virtual CPUs may be dedicated to data path processing in each direction.

3.3 Intelligent network adapter

The exact form factor of this card may vary but the concepts are similar. A chip is placed on a small form factor card with an x8 PCIe connector and multiple 10 G Ethernet ports. This card is then used as inline accelerator that provides both line rate networking and intelligent programmable offload from a host processor subsystem in purpose built appliances and servers. This figure shows an example of a T2080 built as a PCI Express form-factor supporting virtualization through SR-IOV with quad 10 G physical networking interfaces.

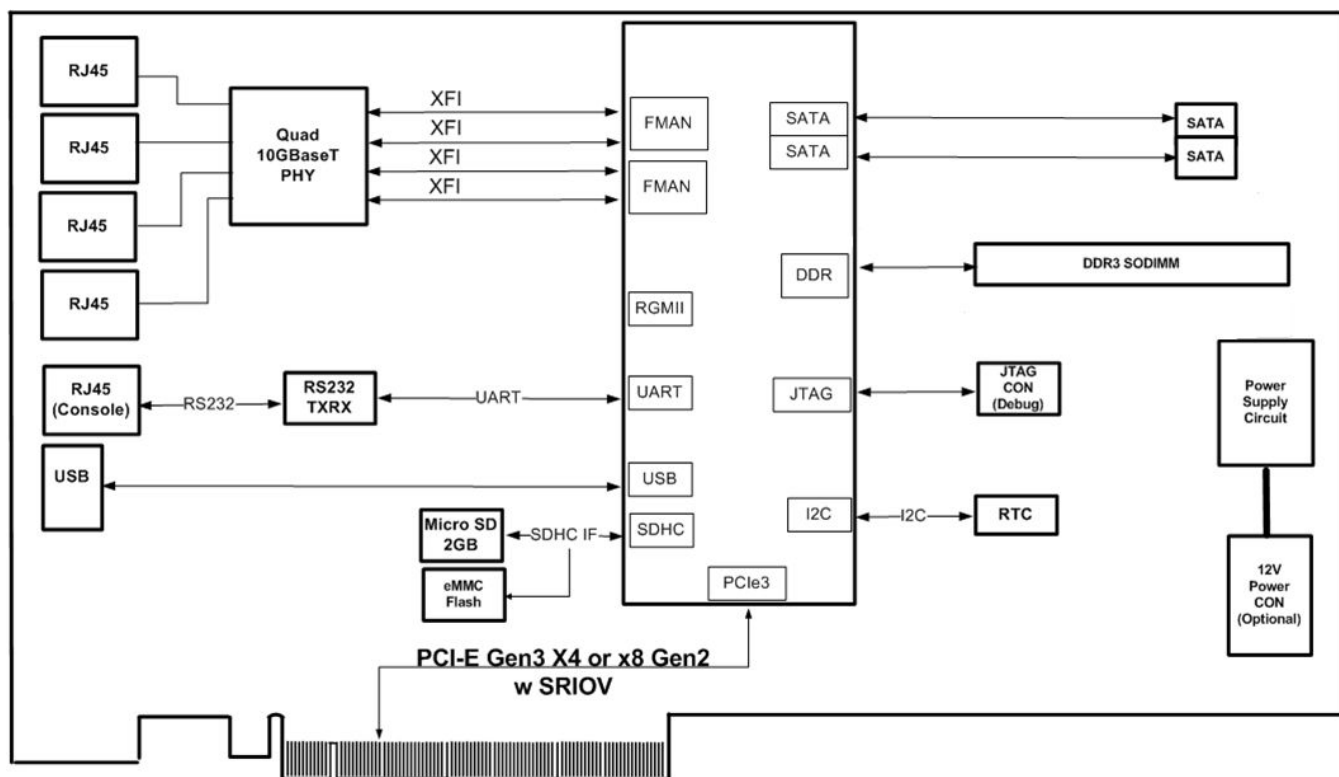


Figure 2. Intelligent network adapter

4 Chip features

This section describes the key features and functionalities of the chip.

4.1 Block diagram

This figure shows the major functional units within the chip.

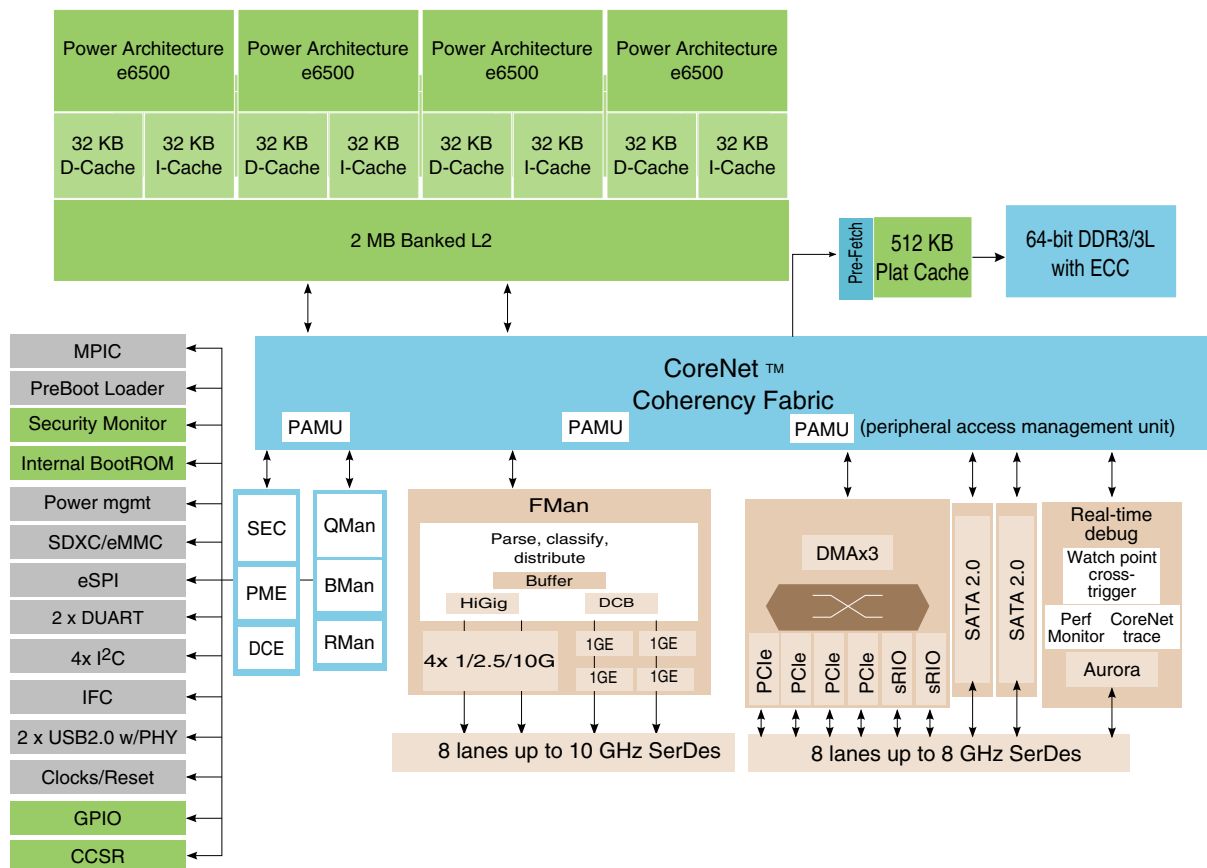


Figure 3. T2080 block diagram

4.2 Features summary

This chip includes the following functions and features:

- 4, dual-threaded e6500 cores built on Power Architecture® technology sharing a 2 MB L2 cache
 - Up to 1.8 GHz with 64-bit ISA support (Power Architecture v2.06-compliant)
- 512 KB CoreNet platform cache (CPC)
- Hierarchical interconnect fabric
 - CoreNet fabric supporting coherent and non-coherent transactions with prioritization and bandwidth allocation amongst CoreNet end-points
 - Queue Manager (QMan) fabric supporting packet-level queue management and quality of service scheduling
- One 32-/64-bit DDR3/3L SDRAM memory controllers with ECC and interleaving support
 - Memory pre-fetch engine
- Data Path Acceleration Architecture (DPAA) incorporating acceleration for the following functions:
 - Packet parsing, classification, and distribution (Frame Manager)
 - Queue management for scheduling, packet sequencing, and congestion management (Queue Manager)
 - Hardware buffer management for buffer allocation and de-allocation (BMan)
 - Cryptography acceleration (SEC 5.2) at up to 10 Gbps
 - RegEx Pattern Matching Acceleration (PME 2.1) at up to 10 Gbps
 - Decompression/Compression Acceleration (DCE) at up to 17.5 Gbps
 - DPAA chip-to-chip interconnect via RapidIO Message Manager (RMAN)
- 16 SerDes lanes at up to 10.3125 GHz
- Eight Ethernet interfaces, supporting combinations of the following:

- Up to four 10 Gbps Ethernet MACs
- Up to eight 1 Gbps Ethernet MACs
- Up to four 2.5 Gbps Ethernet MACs
- High-speed peripheral interfaces
 - Four PCI Express controllers (two support PCIe 2.0 and two support PCIe 3.0)
 - Two Serial RapidIO 2.0 controllers/ports running at up to 5 GHz with Type 11 messaging and Type 9 data streaming support
- Additional peripheral interfaces
 - Two serial ATA (SATA 2.0) controllers
 - Two high-speed USB 2.0 controllers with integrated PHY
 - Enhanced secure digital host controller (SD/SDXC/eMMC)
 - Enhanced serial peripheral interface (eSPI)
 - Four I2C controllers
 - Four 2-pin UARTs or two 4-pin UARTs
 - Integrated Flash controller supporting NAND and NOR flash
- Three eight-channel DMA engines
- Support for hardware virtualization and partitioning enforcement
- QorIQ Platform's Trust Architecture 2.0

4.3 Critical performance parameters

This table lists key performance indicators that define a set of values used to measure SoC operation.

Table 1. Critical performance parameters

Indicator	Values(s)
Top speed bin core frequency	1.8 GHz
Maximum memory data rate	2133 MHz (DDR3) ¹ , 1866.67 MHz for DDR3L <ul style="list-style-type: none"> • 1.5 V for DDR3 • 1.35 V for DDR3L
Integrated flash controller (IFC)	1.8 V
Operating junction temperature range	0-105° C
Extended temperature version	-40–105° C
Package	896-pin, flip-chip plastic ball grid array (FC-PBGA), 25 x 25mm

1. Conforms to JEDEC standard

4.4 Core and CPU clusters

This chip offers four, high-performance 64-bit Power Architecture Book E-compliant cores. Each CPU core supports two hardware threads, which software views as a virtual CPU.

This table shows the computing metrics the core supports.

Table 2. Power architecture metrics

Metric	Per core	Full device
DMIPS	10,800	43,200
Single-precision GFLOPs	14.4	72

Table continues on the next page...

Table 2. Power architecture metrics (continued)

Metric	Per core	Full device
Double-precision GFLOPs	3.6	14.4

The core subsystem includes the following features:

- Up to 1.8 GHz
- Dual-thread with simultaneous multi-threading (SMT)
- 40-bit physical addressing
- L2 MMU
 - Supporting 4 KB pages
 - TLB0; 8-way set-associative, 1024-entries (4 KB pages)
 - TLB1; fully associative, 64-entry, supporting variable size pages and indirect page table entries
- Hardware page table walk
- 64-byte cache line size
- L1 caches, running at core frequency
 - 32 KB instruction, 8-way set-associative
 - 32 KB data, 8-way set-associative
 - Each with data and tag parity protection
- Hardware support for memory coherency
- Five integer units: 4 simple (2 per thread), 1 complex (integer multiply and divide)
- Two load-store units: one per thread
- Classic double-precision floating-point unit
 - Uses 32 64-bit floating-point registers (FPRs) for scalar single- and double-precision floating-point arithmetic
 - Designed to comply with IEEE Std. 754™-1985 FPU for both single and double-precision operations
- AltiVec unit
 - 128-bit Vector SIMD engine
 - 32 128-bit VR registers
 - Operates on a vector of
 - Four 32-bit integers
 - Four 32-bit single precision floating-point units
 - Eight 16-bit integers
 - Sixteen 8-bit integers
 - Powerful permute unit
 - Enhancements include: Move from GPRs to VR, sum of absolute differences operation, extended support for misaligned vectors, handling head and tails of vectors
- Supports Data Path Acceleration Architecture (DPAA) data and context "stashing" into L1 and L2 caches
- User, supervisor, and hypervisor instruction level privileges
- Addition of Elemental Barriers and "wait on reservation" instructions
- New power-saving modes including "drowsy core" with state retention and nap
 - State retention power-saving mode allows core to quickly wake up and respond to service requests
- Processor facilities
 - Hypervisor APU
 - "Decorated Storage" APU for improved statistics support
 - Provides additional atomic operations, including a "fire-and-forget" atomic update of up to two 64-bit quantities by a single access
 - Addition of Logical to Real Address translation mechanism (LRAT) to accelerate hypervisor performance
 - Expanded interrupt model
 - Improved Programmable Interrupt Controller (PIC) automatically ACKs interrupts
 - Implements message send and receive functions for interprocessor communication, including receive filtering
 - External PID load and store facility

- Provides system software with an efficient means to move data and perform cache operations between two disjoint address spaces
- Eliminates the need to copy data from a source context into a kernel context, change to destination address space, then copy the data to the destination address space or alternatively to map the user space into the kernel address space

The arrangement of cores into clusters with shared L2 caches is part of a major re-architecture of the QorIQ cache hierarchy. Details of the banked L2 are provided below.

- 2 MB cache with ECC protection (data, tag, & status)
- 64-byte cache line size
- 16 way, set associative
 - Ways in each bank can be configured in one of several modes
 - Flexible way partitioning per vCPU
 - I-only, D-only, or unified
- Supports direct stashing of datapath architecture data into L2

4.5 Inverted cache hierarchy

From the perspective of software running on an core vCPU, the SoC incorporates a 2-level cache hierarchy. These levels are as follows:

- Level 1: Individual core 32 KB Instruction and Data caches
- Level 2: Locally banked 2 MB cache (configurably shared by other vCPUs in the cluster)

Therefore, the CPC is not intended to act as backing store for the L2s. This allows the CPCs to be dedicated to the non-CPU masters in the SoC, storing DPAA data structures and IO data that the CPUs and accelerators will most likely need.

Although the SoC supports allocation policies that would result in CPU instructions and in data being held in the CPC (CPC acting as vCPU L3), this is not the default. Because the CPC serves fewer masters, it serves those masters better, by reducing the DDR bandwidth consumed by the DPAA and improving the average latency.

4.6 CoreNet fabric and address map

As Freescale's next generation front-side interconnect standard for multicore products, the CoreNet fabric provides the following:

- A highly concurrent, fully cache coherent, multi-ported fabric
- Point-to-point connectivity with flexible protocol architecture allows for pipelined interconnection between CPUs, platform caches, memory controllers, and I/O and accelerators at up to 800 MHz
- The CoreNet fabric has been designed to overcome bottlenecks associated with shared bus architectures, particularly address issue and data bandwidth limitations. The chip's multiple, parallel address paths allow for high address bandwidth, which is a key performance indicator for large coherent multicore processors.
- Eliminates address retries, triggered by CPUs being unable to snoop within the narrow snooping window of a shared bus. This results in the chip having lower average memory latency.

This chip's 40-bit, physical address map consists of local space and external address space. For the local address map, 32 local access windows (LAWs) define mapping within the local 40-bit (1 TB) address space. Inbound and outbound translation windows can map the chip into a larger system address space such as the RapidIO or PCIe 64-bit address environment. This functionality is included in the address translation and mapping units (ATMUs).

4.7 DDR memory controller

The chip offers a single DDR controller supporting ECC protected memories. This DDR controller operates at up to 2133 MHz for DDR3, and, in more power-sensitive applications, up to 1866.667 MHz for DDR3L. Some key DDR controller features are as follows:

- Support x8 and x16 memory widths
 - Programmable support for single-, dual-, and quad-ranked devices and modules
 - Support for both unbuffered and registered DIMMs
 - 4 chip-selects
 - 40-bit address support, up to 1 TB memory
- The SoC can be configured to retain the currently active SDRAM page for pipelined burst accesses. Page mode support of up to 64 simultaneously open pages can dramatically reduce access latencies for page hits. Depending on the memory system design and timing parameters, page mode can save up to ten memory clock cycles for subsequent burst accesses that hit in an active page.
- Using ECC, the SoC detects and corrects all single-bit errors and detects all double-bit errors and all errors within a nibble.
- Upon detection of a loss of power signal from external logic, the DDR controller can put compliant DDR SDRAM DIMMs into self-refresh mode, allowing systems to implement battery-backed main memory protection.
- In addition, the DDR controller offers an initialization bypass feature for use by system designers to prevent re-initialization of main memory during system power-on after an abnormal shutdown.
- Support active zeroization of system memory upon detection of a user-defined security violation.

4.7.1 DDR bandwidth optimizations

Multicore SoCs are able to increase CPU and network interface bandwidths faster than commodity DRAM technologies are improving. As a result, it becomes increasingly important to maximize utilization of main memory interfaces to avoid a memory bottleneck. The SoC's DDR controller Freescale-developed IP, optimized for the QorIQ SoC architecture, with the goal of improving DDR bandwidth utilization by fifty percent when compared to first generation QorIQ SoCs.

The WRITE and READ bandwidth improvement is achieved through target queue enhancements; specifically, changes to the scheduling algorithm, improvements in the bank hashing scheme, support for more transaction re-ordering, and additional proprietary techniques.

4.8 Universal serial bus (USB) 2.0

The two USB 2.0 controllers with integrated PHY provide point-to-point connectivity that complies with the USB specification, Rev. 2.0. Each of the USB controllers with integrated PHY can be configured to operate as a stand-alone host, and one of the controllers (USB #2) can be configured as a stand-alone device, or with both host and device functions operating simultaneously.

Key features of the USB 2.0 controller include the following:

- Complies with USB specification, Rev. 2.0
- Supports high-speed (480 Mbps), full-speed (12 Mbps), and low-speed (1.5 Mbps) operations
- Both controllers support operation as a stand-alone USB host controller
 - Supports USB root hub with one downstream-facing port
 - Enhanced host controller interface (EHCI)-compatible
- Both controllers support operation as a stand-alone USB device
 - Support one upstream-facing port
 - Support six programmable USB endpoints

The host and device functions are both configured to support all four USB transfer types:

- Bulk
- Control
- Interrupt
- Isochronous

4.9 High-speed peripheral interface complex (HSSI)

The SoC offers a variety of high-speed serial interfaces, sharing a set of 16 SerDes lanes. Each interface is backed by a high speed serial interface controller. The SoC has the following types and quantities of controllers:

- Four PCI Express controllers, one Gen 3.0 PCI Express controller with SRIOV, one Gen 3.0 PCI Express controller without SRIOV and two PCI Express Gen 3.0 controllers
- Two Serial RapidIO 2.0
- Two SATA 2.0
- Up to eight Ethernet controllers with various protocols
- Aurora

The features of each high-speed serial controller are described in the subsequent sections. Debug functionality is described in [Debug support](#)."

4.9.1 PCI Express

This chip instantiates four PCI Express controllers, each with the following key features:

- One PCI Express controller supports end-point SR-IOV.
 - Two physical functions
 - 64 virtual functions per physical function
 - Eight MSI-X per either physical function or virtual function
- Two PCI Express controllers support 2.0 (maximum lane width of x8).
- Two PCI Express controllers support 3.0 (maximum lane width of x4).
- Power-on reset configuration options allow root complex or endpoint functionality.
- x8, x4, x2, and x1 link widths support
- Both 32- and 64-bit addressing and 256-byte maximum payload size
- Inbound INTx transactions
- Message signaled interrupt (MSI) transactions

4.9.2 Serial RapidIO

The Serial RapidIO interface is based on the *RapidIO Interconnect Specification, Revision 2.1*. RapidIO is a high-performance, point-to-point, low-pin-count, packet-switched system-level interconnect that can be used in a variety of applications as an open standard. The rich feature set includes high data bandwidth, low-latency capability, and support for high-performance I/O devices as well as message-passing and software-managed programming models. Receive and transmit ports operate independently, and with 2 x 4 Serial RapidIO controllers, the aggregate theoretical bandwidth is 32 Gbps.

The chip offers two Serial RapidIO controllers. Receive and transmit ports operate independently and with 2 x 4 Serial RapidIO controllers; the aggregate theoretical bandwidth is 32 Gbps. The Serial RapidIO controllers can be used in conjunction with "Rapid IO Message Manager (RMAN), as described in [RapidIO Message Manager \(RMan 1.0\)](#)."

Key features of the Serial RapidIO interface unit include the following:

- Support for *RapidIO Interconnect Specification, Revision 2.1* (All transaction flows and priorities.)

Chip features

- 2x, and 4x LP-serial link interfaces, with transmission rates of 2.5, 3.125, or 5.0 Gbaud (data rates of 1.0, 2.0, 2.5, or 4.0 Gbps) per lane
- Auto-detection of 1x, 2x, or 4x mode operation during port initialization
- 34-bit addressing and up to 256-byte data payload
- Support for SWRITE, NWRITE, NWRITE_R and Atomic transactions
- Receiver-controlled flow control
- RapidIO error injection
- Internal LP-serial and application interface-level loopback modes

The Serial RapidIO controller also supports the following capabilities, many of which are leveraged by the RMan to efficient chip-to-chip communication through the DPAA:

- Support for RapidIO Interconnect Specification 2.1, "Part 2: Message Passing Logical Specification"
- Supports RapidIO Interconnect Specification 2.1, "Part 10: Data Streaming Logical Specification"
- Supports RapidIO Interconnect Specification 2.1, "Annex 2: Session Management Protocol"
 - Supports basic stream management flow control (XON/XOFF) using extended header message format
- Up to 16 concurrent inbound reassembly operations
 - One additional reassembly context is reservable to a specific transaction type
- Support for outbound Type 11 messaging
- Support for outbound Type 5 NWRITE and Type 6 SWRITE transactions
- Support for inbound Type 11 messaging
- Support for inbound Type 9 data streaming transactions
- Support for outbound Type 9 data streaming transactions
 - Up to 64 KB total payload
- Support for inbound Type 10 doorbell transactions
 - Transaction steering through doorbell header classification
- Support for outbound Type 10 doorbell transactions
 - Ordering can be maintained with respect to other types of traffic.
- Support for inbound and outbound port-write transactions
 - Data payloads of 4 to 64 bytes

4.9.3 SATA

Each of the SoC's two SATA controllers is compliant with the *Serial ATA 2.6 Specification*. Each of the SATA controllers has the following features:

- Supports speeds: 1.5 Gbps (first-generation SATA), and 3Gbps (second-generation SATA)
- Supports advanced technology attachment packet interface (ATAPI) devices
- Contains high-speed descriptor-based DMA controller
- Supports native command queuing (NCQ) commands
- Supports port multiplier operation
- Supports hot plug including asynchronous signal recovery

4.10 Data Path Acceleration Architecture (DPAA)

This chip includes an enhanced implementation of the QorIQ Datapath Acceleration Architecture (DPAA). This architecture provides the infrastructure to support simplified sharing of networking interfaces and accelerators by multiple CPUs. These resources are abstracted as enqueue/dequeue operations by CPU 'portals' into the datapath. Beyond enabling multicore sharing of resources, the DPAA significantly reduces software overheads associated with high-touch packet-processing operations.

Examples of the types of packet-processing services that this architecture is optimized to support are as follows:

- Traditional routing and bridging
- Firewall
- Security protocol encapsulation and encryption

The functions off-loaded by the DPAA fall into two broad categories:

- Packet distribution and queue-congestion management
- Accelerating content processing

4.10.1 DPAA terms and definitions

The QorIQ Platform's Data Path Acceleration Architecture (henceforth DPAA) assumes the existence of network flows, where a flow is defined as a series of network datagrams, which have the same processing and ordering requirements. The DPAA prescribes data structures to be initialized for each flow. These data structures define how the datagrams associated with that flow move through the DPAA. Software is provided a consistent interface (the software portal) for interacting with hardware accelerators and network interfaces.

All DPAA entities produce data onto frame queues (a process called enqueueing) and consume data from frame queues (dequeuing). Software enqueues and dequeues through a software portal (each vCPU has two software portals), and the FMan, RMan, and DPAA accelerators enqueue/dequeue through hardware portals. This figure illustrates this key DPAA concept.

This table lists common DPAA terms and their definitions.

Table 3. DPAA terms and definitions

Term	Definition	Graphic representation
Buffer	Region of contiguous memory, allocated by software, managed by the DPAA BMan	
Buffer pool	Set of buffers with common characteristics (mainly size, alignment, access control)	
Frame	Single buffer or list of buffers that hold data, for example, packet payload, header, and other control information	
Frame queue (FQ)	FIFO of frames	
Work queue (WQ)	FIFO of FQs	

Table continues on the next page...

Table 3. DPAA terms and definitions (continued)

Term	Definition	Graphic representation
Channel	Set of eight WQs with hardware provided prioritized access	
Dedicated channel	Channel statically assigned to a particular end point, from which that end point can dequeue frames. End point may be a CPU, FMan, PME, or SEC.	-
Pool channel	A channel statically assigned to a group of end points, from which any of the end points may dequeue frames.	

4.10.2 Major DPAA components

The SoC's Datapath Acceleration Architecture, shown in the figure below, includes the following major components:

- Frame Manager (FMan)
- Queue Manager (QMan)
- Buffer Manager (BMan)
- RapidIO Message Manager (RMan 1.0)
- Security Engine (SEC 5.2)
- Pattern Matching Engine (PME 2.1)
- Decompression and Compression Engine (DCE 1.0)

The QMan and BMan are infrastructure components, which are used by both software and hardware for queuing and memory allocation/deallocation. The Frame Managers and RMan are interfaces between the external world and the DPAA. These components receive datagrams via Ethernet or Serial RapidIO and queue them to other DPAA entities, as well as dequeue datagrams from other DPAA entities for transmission. The SEC, PME, and DCE are content accelerators that dequeue processing requests (typically from software) and enqueue results to the configured next consumer. Each component is described in more detail in the following sections.

Freescall's basic NFA capabilities for byte pattern scanning are as follows:

- The PME's regex compiler accepts search patterns using syntax similar to that in software-based regex engines, such as Perl-Compatible Regular Expression (PCRE).
 - Supports Perl meta-characters including wildcards, repeats, ranges, anchors, and so on.
 - Byte patterns are simple matches, such as gabcd123h, existing in both the data being scanned and in the pattern specification database.
- Up to 32 KB patterns of length 1-128 bytes

Freescall's extensions to NFA style pattern matching are principally related to event pattern scanning. Event patterns are sequences of byte patterns linked by 'stateful rules.' Freescall uses event pattern scanning and stateful rule processing synonymously. Stateful rules are hardware instructions by which users define reactions to pattern match events, such as state changes, assignments, bitwise operations, addition, subtraction, and comparisons.

Some key characteristics and benefits of the Stateful Rule extensions include:

- Ability to match patterns across data "work units" or packet boundaries
 - Can be used to correlate patterns, qualify matches (for example, contextual match), or to track protocol state change
- Easily support "greedy" wildcards
 - For example, ABC.*DEF == two patterns tied together by a stateful rule
- Delays the need for software post-processing. Software is alerted after all byte patterns are detected in the proper sequence, rather than any time a byte pattern is detected.
- Implements a significant subset of the regex pattern definition syntax as well as many constructs which cannot be expressed in standard PCRE
- PME 2.1 supports up to 32K stateful rules, linking multiple byte patterns

The PME 2.1 dequeues data from its QMan hardware portal and, based on FQ configuration, scans the data against one of 256 pattern sets, 16 subsets per pattern set.

When the PME finds a byte pattern match, or a final pattern in a stateful rule, it generates a report.

4.10.2.5 RapidIO Message Manager (RMan 1.0)

The RapidIO message manager (RMan) produces and consumes Type 8 Port-write, Type 9 Data Streaming, Type 10 Doorbells and Type 11 Messaging traffic and is capable of producing Type 5 NWRITE and Type 6 SWRITE transactions. For inbound traffic, the RMan supports up to 17 open reassembly contexts as a arbitrary mix of Type 9, and Type 11 traffic.

As ingress packets arrive at the RMan, they are compared against up to 64 classification rules to determine the target queue. These rules support Type 8, 9, 10 and 11 transaction types. They may be wild-carded and are configured as masks over selected header fields. This table lists the fields that are maskable as part of each classification rule.

Table 4. Maskable fields in each classification rule

Classification rule	Field
Transaction types	RapidIO port
	Source device ID
	Destination device ID
	Flow level
Type 9 messaging-specific	Class-of-service (CoS)
	StreamID
Type 11 messaging-specific	Mailbox
	Extended mailbox
	Letter

4.10.2.7 Decompression and Compression Engine (DCE 1.0)

The Decompression and Compression Engine (DCE 1.0) is an accelerator compatible with Datapath Architecture providing lossless data decompression and compression for the QorIQ family of SoCs. The DCE supports the raw DEFLATE algorithm (RFC1951), GZIP format (RFC1952) and ZLIB format (RFC1950). The DCE also supports Base 64 encoding and decoding (RFC4648).

The DEFLATE algorithm is a basic building block for data compression in most modern communication systems. It is used by HTTP to compress web pages, by SSL to compress records, by gzip to compress files and email attachments, and by many other applications.

Deflate involves searching for repeated patterns previously seen in a Frame, computing the length and the distance of the pattern with respect to the current location in the Frame, and encoding the resulting information into a bitstream.

The decompression algorithm involves decoding the bitstream and replaying past data. The Decompression and Compression Engine is architected to minimize the system memory bandwidth required to do decompression and compression of Frames while providing multi-gigabits per second of performance.

Detailed features include the following:

- Deflate; as specified as in RFC1951
- GZIP; as specified in RFC1952
- Zlib; as specified in RFC1950
 - Interoperable with the zlib 1.2.5 compression library
- Compression
 - ZLIB, GZIP and DEFLATE header insertion
 - ZLIB and GZIP CRC computation and insertion
 - Zlib sync flush and partial flush for chunked compression (for example, for HTTP1.1)
 - Four modes of compression
 - No compression (just add DEFLATE header)
 - Encode only using static/dynamic Huffman codes
 - Compress and encode using static Huffman codes
 - Compress and encode using dynamic Huffman codes
 - Uses a 4KB sliding history window
 - Supports Base 64 encoding (RFC4648) after compression
 - Provides at least 2.5:1 compression ratio on the Calgary Corpus
- Decompression supports:
 - ZLIB, GZIP and DEFLATE header removal
 - ZLIB and GZIP CRC validation
 - 32KB history
 - Zlib flush for chunked decompression (for HTTP1.1 for example)
 - All standard modes of decompression
 - No compression
 - Static Huffman codes
 - Dynamic Huffman codes
 - Provides option to return original compressed Frame along with the uncompressed Frame or release the buffers to BMan
 - Does not support use of ZLIB preset dictionaries (FDICT flag = 1 is treated as an error).
 - Base 64 decoding (RFC4648) prior to decompression

The DCE 1.0 is designed to support up to 8.8 Gbps for either compression or decompression, or 17.5 Gbps aggregate at ~4 KB data sizes.

4.11 OCeaN DMA

The OCeaN fabric is used to:

- Transfer general data between two memory locations
- Eight high-speed/high-bandwidth channels
- Basic DMA operation modes (direct, simple chaining)
- Extended DMA operation modes (advanced chaining and stride capability)
- Programmable bandwidth control between channels
- Three priority levels supported for source and destination transactions
- Can be activated using DREQ pin
- Optimized to work with the high speed interfaces
- Address translation and mapping unit (ATMU) which allows to define packet attributes as address/device/flow level/transaction type. ATMU Bypass that allows the descriptor to specify the attributes.

4.12 Serial memory controllers

In addition to the parallel NAND and NOR flash supported by means of the IFC, the chip supports serial flash using eSPI and SD/eSDHC/eMMC card and device interfaces. The SD/eSDHC/eMMC controller includes a DMA engine, allowing it to move data from serial flash to external or internal memory following straightforward initiation by software.

Detailed features of the eSPI controller include the following:

- Supports SPI full-duplex or half-duplex single master mode with four independent chip-selects
- Supports RapidS™ full clock cycle operation, and Winbond dual output read
- Independent, programmable baud-rate generator
- Programmable clock phase and polarity
- Supports four different configurations per chip-select

Detailed features of the SD/eSDHC/eMMC controller include the following:

- Conforms to the *SD Host Controller Standard Specification version 3.0*
- Compatible with the *MMC System Specification version 4.5*
- Compatible with the *SD Memory Card Physical Layer Specification version 3.01*
- Compatible with the *SD - SDIO Card Specification version 2.0*
- Designed to work with eMMC devices as well as SD Memory, SDIO, and SD Combo cards and their variants
- Supports SD UHS-1 speed modes

4.12.1 PreBoot Loader and nonvolatile memory interfaces

The PreBoot Loader (PBL) operates on behalf of a large number of interfaces.

4.12.1.1 PreBoot Loader (PBL)

The PBL's functions include the following:

- Simplifies boot operations, replacing pin strapping resistors with configuration data loaded from nonvolatile memory
- Uses the configuration data to initialize other system logic and to copy data from low speed memory interfaces (I²C, IFC, eSPI, SD/SDXC/eMMC) into fully initialized DDR or other access targets in the chip
- Releases CPU 0 from reset, allowing the boot processes to begin from fast system memory

4.12.1.2 Integrated Flash Controller

The SoC incorporates an Integrated Flash Controller similar to the one used in some previous generation QorIQ SoCs. The IFC supports both NAND and NOR flash, as well as a general purpose memory mapped interface for connecting low speed ASICs and FPGAs.

4.12.1.2.1 NAND Flash features

- x8/x16 NAND Flash interface
- Optional ECC generation/checking
- Flexible timing control to allow interfacing with proprietary NAND devices
- SLC and MLC Flash devices support with configurable page sizes of up to 8 KB
- Support advance NAND commands like cache, copy-back, and multiplane programming
- Boot chip-select (CS0) available after system reset, with boot block size of 8 KB, for execute-in-place boot loading from NAND Flash
- Up to terabyte Flash devices supported

4.12.1.2.2 NOR Flash features

- Data bus width of 8/16
- Compatible with asynchronous NOR Flash
- Directly memory mapped
- Supports address data multiplexed (ADM) NOR device
- Flexible timing control allows interfacing with proprietary NOR devices
- Boot chip-select (CS0) available at system reset

4.12.1.2.3 General-purpose chip-select machine (GPCM)

The IFC's GPCM supports the following features:

- Normal GPCM
 - Support for x8/16-bit device
 - Compatible with general purpose addressable device, for example, SRAM and ROM
 - External clock is supported with programmable division ratio (2, 3, 4, and so on, up to 16)
- Generic ASIC Interface
 - Support for x8/16-bit device
 - Address and Data are shared on I/O bus
 - Following address and data sequences are supported on I/O bus:
 - 16-bit I/O: AADD
 - 8-bit I/O: AAAADDDD

4.13 Resource partitioning and QorIQ Trust Architecture

Consolidation of discrete CPUs into a single, multicore chip introduces many opportunities for unintended resource contentions to arise, particularly when multiple, independent software entities reside on a single chip. A system may exhibit erratic behavior if multiple software partitions cannot effectively partition resources. Device consolidation, combined with a trend toward embedded systems becoming more open (or more likely to run third-party or open-source software on at least one of the cores), creates opportunities for malicious code to enter a system.

This chip offers a new level of hardware partitioning support, allowing system developers to ensure software running on any CPU only accesses the resources (memory, peripherals, and so on) that it is explicitly authorized to access. This section provides an overview of the features implemented in the chip that help ensure that only trusted software executes on the CPUs, and that the trusted software remains in control of the system with intended isolation.

4.13.1 Core MMU, UX/SX bits, and embedded hypervisor

The chip's first line of defense against unintended interactions amongst the multiple CPUs/OSes is each core vCPU's MMU. A vCPU's MMU is configured to determine which addresses in the global address map the CPU is able to read or write. If a particular resource (memory region, peripheral device, and so on) is dedicated to a single vCPU, that vCPU's MMU is configured to allow access to those addresses (on 4 KB granularity); other vCPU MMUs are not configured for access to those addresses, which makes them private. When two vCPUs need to share resources, their MMUs are both configured so that they have access to the shared address range.

This level of hardware support for partitioning is common today; however, it is not sufficient for many core systems running diverse software. When the functions of multiple discrete CPUs are consolidated onto a single multicore chip, achieving strong partitioning should not require the developer to map functions onto vCPUs that are the exclusive owners of specific platform resources. The alternative, a fully open system with no private resources, is also unacceptable. For this reason, the core's MMU also includes three levels of access permissions: user, supervisor (OS), and hypervisor. An embedded hypervisor (for example, KVM, XEN, QorIQ ecosystem partner hypervisor) runs unobtrusively beneath the various OSes running on the vCPUs, consuming CPU cycles only when an access attempt is made to an embedded hypervisor-managed shared resource.

The embedded hypervisor determines whether the access should be allowed and, if so, proxies the access on behalf of the original requestor. If malicious or poorly tested software on any vCPU attempts to overwrite important device configuration registers (including vCPU's MMU), the embedded hypervisor blocks the write. High and low-speed peripheral interfaces (PCI Express, UART), when not dedicated to a single vCPU/partition, are other examples of embedded hypervisor managed resources. The degree of security policy enforcement by the embedded hypervisor is implementation-dependent.

In addition to defining regions of memory as being controlled by the user, supervisor, or hypervisor, the core MMU can also configure memory regions as being non-executable. Preventing CPUs from executing instructions from regions of memory used as data buffers is a powerful defense against buffer overflows and other runtime attacks. In previous generations of Power Architecture, this feature was controlled by the NX (no execute) attribute. In new Power Architecture cores such as the e6500 core, there are separate bits controlling execution for user (UX) and supervisor (SX).

4.13.2 Peripheral access management unit (PAMU)

MMU-based access control works for software running on CPUs; however, these are not the only bus masters in the SoC. Internal components with bus mastering capability (FMan, RMan, PCI Express controller, PME, SEC, and so on) also need to be prevented from reading and writing to certain memory regions. These components do not spontaneously generate access attempts; however, if programmed to do so by buggy or malicious software, any of them could read or write sensitive data registers and crash the system. For this reason, the SoC also includes a distributed function referred to as the peripheral access management unit (PAMU).

PAMUs provide address translation and access control for all non-CPU initiators in the system. PAMU access control is based on the logical I/O device number (LIODN) advertised by a bus master for a given transaction. LIODNs can be static (for example, PCI Express controller #1 always uses LIODN 123) or they can be dynamic, based on the ID of the CPU that programmed the initiator (for example, the SEC uses LIODN 456 because it was given a descriptor by vCPU #2). In the dynamic example, the SoC architecture provides positive identification of the vCPU programming the SEC, preventing LIODN spoofing.

4.13.3 IO partitioning

The simplest IO configuration in chips running multiple independent software partitions is to dedicate specific IO controllers (PCI Express, SATA, Serial RapidIO controllers) to specific vCPUs. The core MMUs and PAMUs can enforce these access permissions to insure that only the software partition owning the IO is able to use it. The obvious problem with this approach is that there are likely to be more software partitions wanting IO access than there are IO controllers to dedicate to each.

Chip features

Safe IO sharing can be accomplished through the use of a hypervisor; however, there is a performance penalty associated with virtual IO, as the hypervisor must consume CPU cycles to schedule the IO requests and get the results back to the right software partition.

The DPAA (described in [Data Path Acceleration Architecture \(DPAA\)](#)) was designed to allow multiple partitions to efficiently share accelerators and IOs, with its major capabilities centered around sharing Ethernet ports. These capabilities were enhanced in the chip with the addition of FMan storage profiles. The chip's FMans perform classification prior to buffer pool selection, allowing Ethernet frames arriving on a single port to be written to the dedicated memory of a single software partition. This capability is fully described in [Receiver functionality: parsing, classification, and distribution](#)."

The addition of the RMan extends the chip's IO virtualization by allowing many types of traffic arriving on Serial RapidIO to enter the DPAA and take advantage of its inherent virtualization and partitioning capabilities.

The PCI Express protocol lacks the PDU semantics found in Serial RapidIO, making it difficult to interwork between PCI Express controllers and the DPAA; however, PCI Express has made progress in other areas of partition. The Single Root IO Virtualization specification, which the chip supports as an endpoint, allows external hosts to view the chip as multiple four physical functions (PFs), where each PF supports up to 64 virtual functions (VFs). Having multiple VFs on a PCI Express port effectively channelizes it, so that each transaction through the port is identified as belonging to a specific PF/VF combination (with associated and potentially dedicated memory regions). Message signalled interrupts (MSIs) allow the external Host to generate interrupts associated with a specific VF.

4.13.4 Secure boot and sensitive data protection

The core MMUs and PAMU allow the SoC to enforce a consistent set of memory access permissions on a per-partition basis. When combined with an embedded hypervisor for safe sharing of resources, the SoC becomes highly resilient to poorly tested or malicious code. For system developers building high reliability/high security platforms, rigorous testing of code of known origin is the norm.

For this reason, the SoC offers a secure boot option, in which the system developer digitally signs the code to be executed by the CPUs, and the SoC insures that only an unaltered version of that code runs on the platform. The SoC offers both boot time and run time code authenticity checking, with configurable consequences when the authenticity check fails. The SoC also supports protected internal and external storage of developer-provisioned sensitive instructions and data. For example, a system developer may provision each system with a number of RSA private keys to be used in mutual authentication and key exchange. These values would initially be stored as encrypted blobs in external non-volatile memory; but, following secure boot, these values can be decrypted into on-chip protected memory (portion of platform cache dedicated as SRAM). Session keys, which may number in the thousands to tens of thousands, are not good candidates for on-chip storage, so the SoC offers session key encryption. Session keys are stored in main memory, and are decrypted (transparently to software and without impacting SEC throughput) as they are brought into the for decryption of session traffic.

4.14 Advanced power management

Power dissipation is always a major design consideration in embedded applications; system designers need to balance the desire for maximum compute and IO density against single-chip and board-level thermal limits.

Advances in chip and board level cooling have allowed many OEMs to exceed the traditional 30 W limit for a single chip, and Freescale's flagship T4240 multicore chip, has consequently retargeted its maximum power dissipation. A top-speed bin T4240 dissipates approximately 2x the power dissipation of the P4080; however, the T4240 increases computing performance by ~4x, yielding a 2x improvement in DMIPs per watt.

Junction temperature is a critical factor in comparing embedded processor specifications. Freescale specs max power at 105C junction, standard for commercial, embedded operating conditions. Not all multicore chips adhere to a 105C junction for specifying worst case power. In the interest of normalizing power comparisons, the chip's typical and worst case power (all CPUs at 1.8 GHz) are shown at alternate junction temperatures.

To achieve the previously-stated 2x increase in performance per watt, the chip implements a number of software transparent and performance transparent power management features. Non-transparent power management features are also available, allowing for significant reductions in power consumption when the chip is under lighter loads; however, non-transparent power savings are not assumed in chip power specifications.

4.14.1 Transparent power management

This chip's commitment to low power begins with the decision to fabricate the chip in 28 nm bulk CMOS. This process technology offers low leakage, reducing both static and dynamic power. While 28 nm offers inherent power savings, transistor leakage varies from lot to lot and device to device. Leakier parts are capable of faster transistor switching, but they also consume more power. By running devices from the leakier end of the process spectrum at less than nominal voltage and devices from the slower end of the process spectrum at higher nominal voltage, T2080-based systems can achieve the required operating frequency within the specified max power. During manufacturing, Freescale will determine the voltage required to achieve the target frequency bin and program this Voltage ID into each device, so that initialization software can program the system's voltage regulator to the appropriate value.

Dynamic power is further reduced through fine-grained clock control. Many components and subcomponents in the chip automatically sleep (turn off their clocks) when they are not actively processing data. Such blocks can return to full operating frequency on the clock cycle after work is dispatched to them. A portion of these dynamic power savings are built into the chip max power specification on the basis of impossibility of all processing elements and interfaces in the chip switching concurrently. The percent switching factors are considered quite conservative, and measured typical power consumption on QorIQ chips is well below the maximum in the data sheet.

As noted in [Frame Manager and network interfaces](#), the chip supports Energy-Efficient Ethernet. During periods of extended inactivity on the transmit side, the chip transparently sends a low power idle (LPI) signal to the external PHY, effectively telling it to sleep.

Additional power savings can be achieved by users statically disabling unused components. Developers can turn off the clocks to individual logic blocks (including CPUs) within the chip that the system is not using. Based on a finite number of SerDes, it is expected that any given application will have some inactive Ethernet MACs, PCI Express, or serial RapidIO controllers. Re-enabling clocks to a logic block generally requires a chip reset, which makes this type of power management infrequent (effectively static) and transparent to runtime software.

4.14.2 Non-transparent power management

Many load-based power savings are use-case specific static configurations (thereby software transparent), and were described in the previous section. This section focuses on SoC power management mechanisms, which software can dynamically leverage to reduce power when the system is lightly loaded. The most important of these mechanisms involves the cores.

A full description of core low-power states with proper names is provided in the SoC reference manual. At a high level, the most important of these states can be viewed as "PH10" and "PH20," described as follows. Note that these are relative terms, which do not perfectly correlate to previous uses of these terms in Power Architecture and other ISAs:

- In PH10 state CPU stops instruction fetches but still performs L1 snoops. The CPU retains all state, and instruction fetching can be restarted instantly.
- In PH20 state CPU stops instruction fetches and L1 snooping, and turns off all clocks. Supply voltage is reduced, using a technique Freescale calls State Retention Power Gating (SRPG). In the "napping" state, a CPU uses ~75% less power than a fully operational CPU, but can still return to full operation quickly (~100 platform clocks).

The core offers two ways to enter these (and other) low power states: registers and instructions.

As the name implies, register-based power management means that software writes to registers to select the CPU and its low power state. Any CPU with write access to power management registers can put itself, or another CPU, into a low power state; however, a CPU put into a low power state by way of register write cannot wake itself up.

A.5 T2081 Signal Differences

SerDes 2 signals described in [Signals Overview](#) are not supported on T2081.

A.6 SerDes Assignments

The following notation conventions are used in the table:

- XFI_m indicates XFI (1 lane @10.3125 Gbps), “m” indicates MAC on the Frame Manager. For example, “XFI9” indicates XFI using MAC 9.
- SGMII notation :
 - *sgm* means SGMII @ 1.25 Gbps where “m” indicates which MAC on the Frame Manager. For example, “SG3” indicates SGMII for MAC 3 at 1.25 Gbps.
 - *sgm* means SGMII @3.125Gbps where “m” indicates which MAC on the Frame Manager. For example, “SG3” indicates SGMII for MAC 3 at 3.25 Gbps.
- PCIe notation :
 - PCI_m is PCIe @ 5/2.5 Gbps, m indicates the PCIe controller number.
 - *PCI_m* is PCIe @ 8/5/2.5 Gbps, m indicates the PCIe controller number.
- Per lane PLL mapping: 1-PLL1, 2-PLL2

SerDes Networking Options:

Table A-5. SerDes

SRDS_PR TCL_S1	A	B	C	D	E	F	G	H	Per lane PLL mapping
6E	XFI9	XFI10	SG1	SG2	PEX4		SG5	SG6	11222222
AA	PEX3				PEX4				11111111
BC	PEX3		SG1	SG2	PEX4				11111111
C8	PEX3	SG10	SG1	SG2	PEX4		SG5	SG6	11221111
CA	PEX3	SG10	SG1	SG2	PEX4	SG4	SG5	SG6	11221111
D6	PEX3	SG10	SG1	SG2	PEX4		SG5	SG6	11112211
DE	PEX3				PEX4	PEX1	PEX2	SG6	11111111
E0	PEX3				PEX4	PEX1	SG5	SG6	11111111
F2	PEX3	SG10	SG1	SG2	PEX4	PEX1	PEX2	SG6	11111111
F8	PEX3	SG10	SG1	SG2	PEX4	PEX1	PEX2	SG6	11221111
FA	PEX3	SG10	SG1	SG2	PEX4	PEX1	SG5	SG6	11221111
6C	XFI9	XFI10	SG1	SG2	PEX4				11222222
70	XFI9	XFI10	SG1	SG2	PEX4	SG4	SG5	SG6	11222222



Appendix B Revision history

B.1 Revision history

This table provides a revision history for this content.

Table B-1. Revision history

Rev. number	Date	Substantive change(s)
0	04/2014	Initial public release